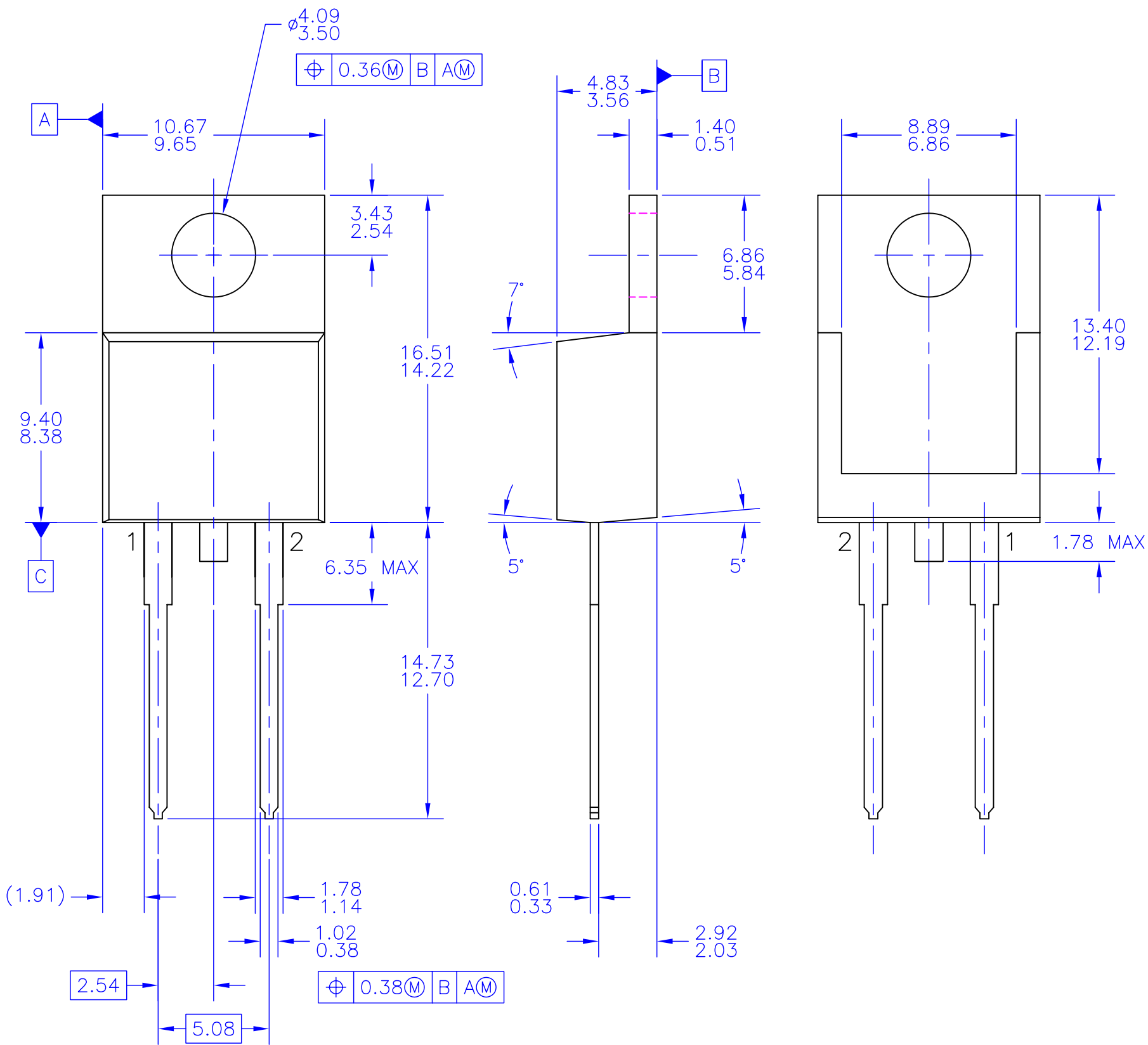


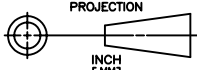
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REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	—	22SEP2004	OS.JEON
B	ADD HOLE POS TOL & LD POS TOL; ADD BACK HEAT SINK DIMS $8.89^{+0.56}_{-0.81}$ & $13.40^{+0.51}_{-0.63}$; CHG LD THICK FR $0.36^{+0.05}_{-0.30}$ TO 0.33 ; CHG LD CUT DIM FR 0.30 MAX TO 1.78 MAX; CHG HEAT SINK THICK FR $1.14^{+0.40}_{-0.51}$ TO 0.51 ; CHG PKG DRAFT ANGLE FR 3° TO 5° ; ADD NOTE D,E&F; CHG NOTE A JEDEC REF.	CB/042/05	23MAR2005	RCM



NOTES: UNLESS OTHERWISE SPECIFIED

- A) REFERENCE JEDEC, TO-220, ISSUE K, VARIATION AC, DATED APRIL 2002.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE INCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D) DIMENSIONING AND TOLERANCING PER ANSI Y14.5 – 1973
- E) PRESENCE OF TRIMMED CENTER LEAD IS OPTIONAL

APPROVALS		DATE		 FAIRCHILD SEMICONDUCTOR™ CEBU PHILIPPINES	
DRAWN: J. GOMEZ		23MAR2005			
CHECKED: R. MANABIT					
APPROVED: M. GESTOLE					
G.S. BAJE		TO-220, MOLDED, 2LD			
		SCALE 5:1	SIZE A3	DRAWING NUMBER MKT-TO220A02	REV B
		FORMERLY: N/A		SHEET : 1 OF 1	